

<b>Notice of References Cited</b>			Application No. 09/259,849	Applicant(s) Farrar		
			Examiner Bernard Souw	Group Art Unit 2814	Page 1 of 1	
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	DOCUMENT NO.	DATE	NAME		CLASS	SUBCLASS
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B	5,969,422 ✓	10/1999	Ting et al.		257	762
C	5,968,333 ✓	10/1999	Nogami et al.		205	184
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E	5,893,752 ✓	04/1999	Zhang et al.		438	687
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<b>NON-PATENT DOCUMENTS</b>						
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